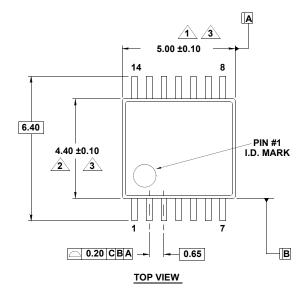
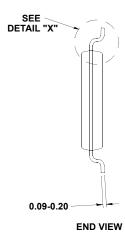
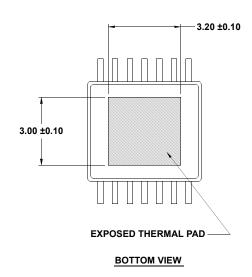
Package Outline Drawing

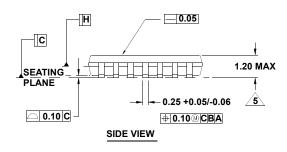
M14.173A

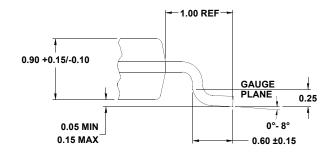
14 LEAD HEATSINK THIN SHRINK SMALL OUTLINE PACKAGE (HTSSOP) Rev 2, 10/09



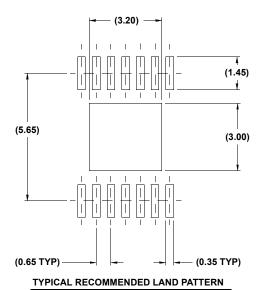








DETAIL "X"



NOTES:

- Dimension does not include mold flash, protrusions or gate burrs.
 Mold flash, protrusions or gate burrs shall not exceed 0.15 per side.
- 2. Dimension does not include interlead flash or protrusion. Interlead flash or protrusion shall not exceed 0.25 per side.
- 3. Dimensions are measured at datum plane H.
- 4. Dimensioning and tolerancing per ASME Y14.5M-1994.
- Dimension does not include dambar protrusion. Allowable protrusion shall be 0.80mm total in excess of dimension at maximum material condition. Minimum space between protrusion and adjacent lead is 0.07mm.
- 6. Dimension in () are for reference only.
- 7. Conforms to JEDEC MO-153, variation AB-1.

